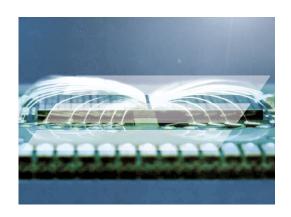
Large Area Hybrid Wire Bonder

64/66000 G5



The 5th generation of F&K Delvotec's fine and heavy wire bonders offers utmost flexibility for all aluminium and gold wire applications from 17 to 600 μ m. Optimum bond quality is ensured by the vibration-free machine frame and high performance bond heads with integrated impedance measurement and bond process control.





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SPECIFICATIONS Bond areas 220 mm x 100 mm

220 mm x 220 mm

Z-range 50 mm

Die count Over 200 per circuit standard

Pattern recognition Travelling CCD camera and Cognex 8000

> Control Pentium M[™] processor with UNIX-based operating system

Data transfer Range of standard options for export of quality

control data

Network capability TCP/IP network standard built in, allowing remote access

for diagnosis, service and software maintenance

Ethernet and SMEMA interface, SECS/GEM

HSMS capability

Quality assurance Impedance analysis, Bond Process Control

for extremely uniform bonds

Optional: pull tester integrated in bond head

Overall dimensions

machine only 62 x 120 x 180 cm (W x D x H)

100 - 120; 200 - 240 VAC, 50 - 60 Hz, Line requirements

0.5 kVA single phase

4 - 8 bar (rel.) / < -0.8 bar (rel.)Compressed air/vacuum

FINE WIRE BOND HEAD Wire diameter 17 to 100 μm

> Wire feed Motor-driven 2" spool

> > Wire feed angle 45° standard, 60° or 90° optional,

1" bond tool

Digital ultrasonic system Programmable digital generator 30...250 kHz

HEAVY WIRE BOND HEAD Wire diameter 100 to 600 µm

> Wire feed Motor driven 3" and 4" wire spool

> > Snap-on wire guide Front and back-cut unit

2 ¾ " bond tool

Digital ultrasonic system Programmable digital generator 40...120 kHz

MATERIAL INPUT Substrate types Leadframes, PCBs, boats, carriers etc.

> Component handling Manual, semi-automatic, automatic,

magazine to magazine or in-line

OPERATING DATA Placement accuracy Typically better than +/- 5 µm @ 3 sigma